Conical Fiber Chamber Liner Concept Illustration SRIM Calculations W and C Needles Test Venues

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Cone-Wall Chamber Liner

- He implantation on the LFE chamber wall will eventually blister and exfoliate <u>smooth</u> surfaces. For longer lifetime, we consider <u>rough</u> chamber liners that have large surface area to reduce local fluence and thereby increase lifetime.
- Velvet liners investigated by HAPL show improved survivability of sloping surfaces and sharp tips. Blunt tips and horizontal fibers damage faster.
- The <u>cone-wall</u> is a highly ordered velvet consisting of closely-packed parallel needles with sharp tips and strictly conical surfaces. Benefits are...
 - Large surface area enhancements are achievable. Local surface fluence is thus reduced, typically 10-100x.
 - LFE radiation emanating from the target impinges at grazing incidence on the cones, resulting in shallower implantation, higher backscatter, and higher sputter yield





Scale Considerations



Thermal Response

Thermal resistance of L = 3 mm cone-wall is low, resulting in <10 K temperature drop. 10x thicker wall may offer lifetime benefits offsetting increased thermal resistance.

Average transient surface T rise is reduced by the factor $1/\alpha$ =L/R ~ 0.03, greatly reducing surface thermal fatigue.

Emissivity and absorptivity of the cone-wall is high (>90%), facilitating radiative heat transfer.



Grazing Incidence Effects

SRIM calcs for 3.45 MeV He on W At normal incidence... He ion range ~5.0 µm 0.0 backscatter 0.0 sputter yield

> At 10 mrad incidence... He ion range ~0.6 μm >0.7 backscatter >0.3 sputter yield







Table of Yield, Backscatter, Range

SRIM 2008.03	Vary Energy and incidence Angle				
Modeling: —	Energy (keV):	<u>3450</u>	<u>700</u>	<u>30</u>	
Ion Angle (deg): 0					
Π	Sputter Yield (atoms/ion):	0	0.0007	0.032	
As energy	Backscatter Fraction (ions/ion):	0.0010	0.0037	0.152	
	Ion Average Depth (um):	5.03	1.0	0.0796	
decreases	Ion Angle (deg): 85				
Sputtering	Sputter Yield (atoms/ion):	0.029	0.165	0.708	
	Backscatter Fraction (ions/ion):	0.2434	0.475	0.694	
increases	Ion Average Depth (um):	0.6844	0.2667	0.0551	
Backscatter \downarrow	Ion Angle (deg): 89.5				
increases	Sputter Yield (atoms/ion):	0.316	0.482	0.489	
	Backscatter Fraction (ions/ion):	0.732	0.786	0.829	
Range	Ion Average Depth (um):	0.5637	0.2439	0.0548	
decreases					

Materials and Processing

H.

HAPL Chamber Liner

Sputter Erosion Behavior (Speculation)

Sputtered cone atoms will redep primarily on neighboring cones; comparatively little will sputter across the chamber.

Cone shapes will gradually evolve. Tips will likely recede and become less sharp. The base of the cones may densify.

Very sharp cones (θ < 10 mrad) cause high backscatter (hence multiple scatterings for each He), and high sputter yield, resulting in faster deformation of the cones.

Optimum life for cone-wall is likely to occur for aspect ratio in the range L/R = 10-100







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W Needle Surface

Heat-treated W wire Ground surface No grain structure revealed





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Carbon Needle Option

ESLI fabricates carbon fiber velvets, etched to sharp tips, approximately conical for L = 1 mm, R = 17 μ m

ESLI 35-µm mesophase pitch fiber tapered to submicron radius tip





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Test Objectives 2008

Investigate discrete W needles having L/R ~ 30 Options: C needles; Needle Clusters; Different Angles; other W types

Observe erosion and damage of discrete vertical needles...

Mass loss	Microbalance
Dulling of tip	\mathbf{SEM}
Shaft erosion	\mathbf{SEM}
Blistering	SEM, FIB

Compare with modeling results (e.g. SRIM)

He Implantation Test FacilitiesSNL/RHEPPpulsed 0.7 MeV; incidence ~ 0.2 radUW/HELIOShigh fluence 30 keV, collimated (TBD)



Conclusions

Benefits of mini-cone chamber wall liner

Surface area enhancement $\alpha = 10-100$, all accessible by line of sight, reduces flux and fluence correspondingly

- Reduced blistering/exfoliation
- ➢ Reduced transient T excursion

Radiation arrives at grazing incidence

- Potentially less damage by high energy ion implantation
- Shallow implantation, high backscatter, high sputter
- Potentially high rate of deformation as cone atoms migrate downward

Issues

Wear, redep deformation Tip fragility and repair Manufacturability

Tests planned in coming months

He bombardment of discrete vertical W, and possibly C, cones

